



## Product/Process Change Notice - PCN 22\_0178 Rev. C

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

*Note: Revised fields are indicated by a red field name. See Appendix B for revision history.*

<b>PCN Title:</b>	UTAC Thailand as an Alternate Assembly Site and UTAC Singapore as an Alternate Test Site for Select (LFCSP) Products
<b>Publication Date:</b>	09-May-2023
<b>Effectivity Date:</b>	11-Aug-2023 <i>(the earliest date that a customer could expect to receive changed material)</i>
<b>Revision Description:</b>	Revised Qualification Report and Added Test Cpk Report

### Description Of Change:

Analog Devices will be utilizing UTAC Thailand as an alternate assembly site and UTAC Singapore as an alternate test site for select products in LFCSP packages.

See attached Material\_Change\_Description in the supporting documents section of this PCN for details regarding change to mold compound and die attach material.

Reference the attached qualification report for the material set used by UTAC Thailand for the LFCSP package.

### Reason For Change:

Adding capacity to ensure continuity of supply in order to meet customer demand.

### Impact of the change (positive or negative) on fit, form, function & reliability:

There are no changes to fit, form, functionality or reliability.

### Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

Test correlation and validation has been performed per ADI's standard product site to site and/or platform change correlation procedure. See attached Qualification Report.

### Supporting Documents

**Attachment 1: Type:** Qualification Results Summary

[ADI\\_PCN\\_22\\_0178\\_Rev\\_C\\_ADI\\_PCN\\_22\\_0178\\_Rev\\_B\\_Qualification\\_Report.pdf...](#)

**Attachment 2: Type:** Test Correlation Report

[ADI\\_PCN\\_22\\_0178\\_Rev\\_C\\_AD2426W\\_AD24227W\\_AD24228W\\_Test\\_Site\\_Test\\_Correla...](#)

**Attachment 3: Type:** Detailed Change Description

[ADI\\_PCN\\_22\\_0178\\_Rev\\_C\\_Material\\_Change\\_Description.pdf...](#)

**Attachment 4: Type:** Delta Qualification Matrix

[ADI\\_PCN\\_22\\_0178\\_Rev\\_C\\_PCN-Delta-Qualification-Matrix-ZVEI-5\\_0\\_14\\_2.xls...](#)

**Attachment 5: Type:** Test Correlation Report

[ADI\\_PCN\\_22\\_0178\\_Rev\\_C\\_AD2428W\\_Assembly\\_Site\\_Test\\_Correlation\\_Report.pd...](#)

Note: If applicable, the device material declaration will be updated due to material change.

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**ADI Contact Information:**

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

<b>Americas:</b>	<b>Europe:</b>	<b>Japan:</b>	<b>Rest of Asia:</b>
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_ROA@analog.com

## Appendix A - Affected ADI Models:

### Existing Parts - Product Family / Model Number (25)

AD2426W / AD2426WCCSZ	AD2426W / AD2426WCCSZ-RL	AD2426W / AD2426WCCSZ01	AD2426W / AD2426WCCSZ01-RL	AD2427W / AD2427WCCSZ
AD2427W / AD2427WCCSZ-RL	AD2427W / AD2427WCCSZ01	AD2427W / AD2427WCCSZ01-RL	AD2428W / AD2428WCCSZ	AD2428W / AD2428WCCSZ-RL
AD2428W / AD2428WCCSZ01	AD2428W / AD2428WCCSZ01-RL	AD2428W / AD2428WCCSZ02	AD2428W / AD2428WCCSZ02-RL	AD2428W / ADW95179Z-10
AD2428W / ADW95179Z-10RL	AD2428W / ADW95185Z-01	AD2428W / ADW95185Z-01RL	AD2428W / ADW95186Z-01	AD2428W / ADW95186Z-01RL
AD2428W / ADW95187Z-01	AD2428W / ADW95187Z-01RL	AD2428W / ADW95190Z	AD2428W / ADW95190Z-RL	AD2428W / ADW95038Z-RL

**Appendix B - Revision History:**

<b>Rev</b>	<b>Publish Date</b>	<b>Effectivity Date</b>	<b>Rev Description</b>
Rev. -	05-Dec-2022	09-Mar-2023	Initial Release.
Rev. A	24-Jan-2023	28-Apr-2023	Add Material Change Description. Add Revised Delta Qualification.
Rev. B	04-Apr-2023	07-Jul-2023	Revised Qualification Report for Mold Compound Change.
Rev. C	09-May-2023	11-Aug-2023	Revised Qualification Report and Added Test Cpk Report